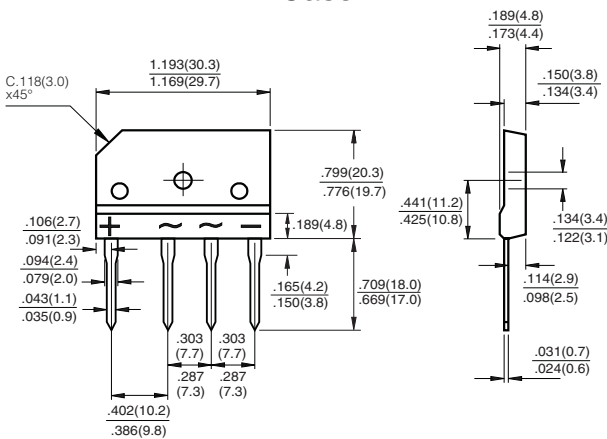



## 25 Amp. Glass Passivated Bridge Rectifier

<p style="text-align: center;"><b>Plastic Case</b></p>  <ul style="list-style-type: none"> <li>• <b>Mounting Instructions</b></li> <li>• High temperature soldering guaranteed: 260 °C – 10 sc.</li> <li>• Recommended mounting torque: 8 Kg.cm.</li> </ul>	<p><b>Voltage</b> 600 to 1000 V</p> <p><b>Current</b> 25 A</p>  <ul style="list-style-type: none"> <li>• <b>Glass Passivated Junction Chips.</b></li> <li>• The plastic material carries U/L recognition 94 V-O.</li> <li>• Lead and polarity identifications.</li> <li>• Case: Molded Plastic.</li> <li>• Ideal for printed circuit board</li> <li>• High surge current</li> </ul>
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### Maximum Ratings, according to IEC publication No. 134

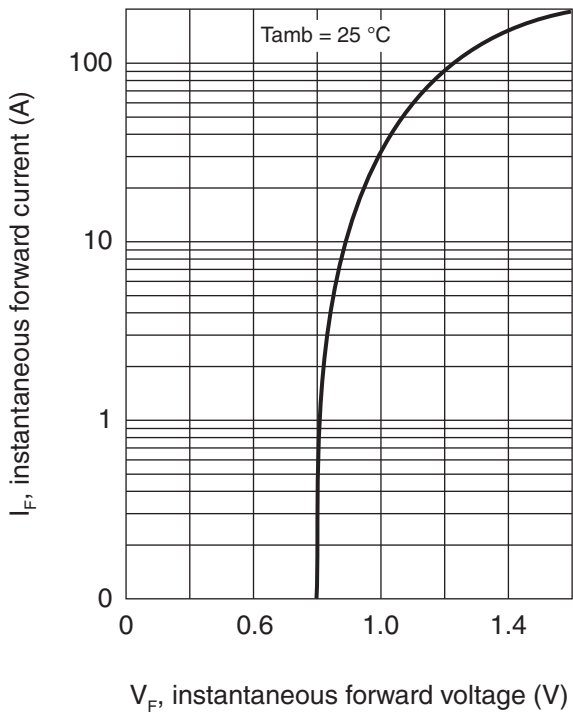
		D25XB 40	D25XB 60	D25XB 80	D25XB 100
$V_{RRM}$	Peak recurrent reverse voltage (V)	400	600	800	1000
$V_{RMS}$	Maximum RMS Voltage (V)	280	420	560	700
$I_{F(AV)}$	Max. Average forward current with heatsink without heatsink	25.0 A at $T_c$ : 75 °C 3.2 A at 25 °C			
$I_{FSM}$	8.3 ms. peak forward surge current (Jedec Method)	300 A			
$I^2t$	Current squared time (rating for fusing) (1ms.<t<10ms. $T_c = 25^\circ C$ )	373 A <sup>2</sup> sec			
$V_{DIS}$	Dielectric strength (terminals to case, AC 1 min.)	2500 V			
$T_j$	Operating temperature range	-55 to +150 °C			
$T_{stg}$	Storage temperature range	-55 to +150 °C			

### Electrical Characteristics at $T_{amb} = 25\text{ }^\circ C$

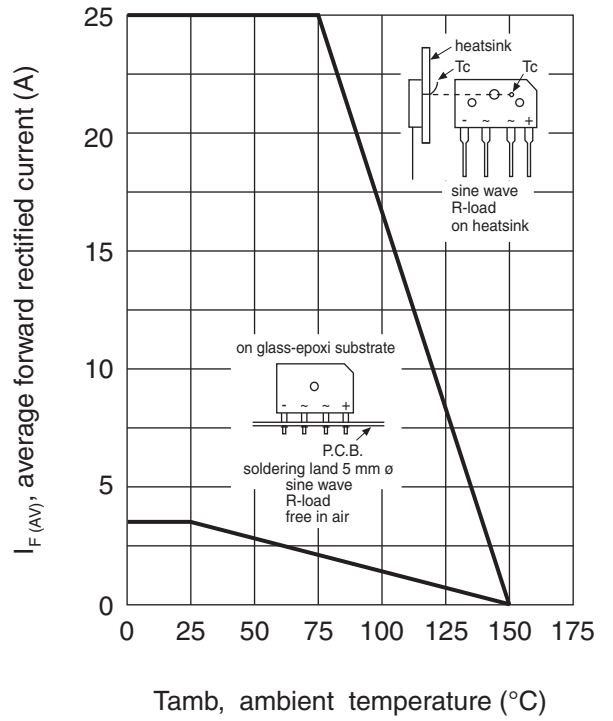
$V_F$	Max. forward voltage drop per diode at $I_F = 25\text{ A}$	1.10 V
$I_R$	Max. instantaneous reverse current at $V_{RRM}$	5 $\mu A$
$R_{th(j-c)}$	MAXIMUM THERMAL RESISTANCE Junction-case. With Heatsink.	1 °C/W
$R_{th(j-a)}$	Junction-Ambient. Without Heatsink.	35 °C/W

**Rating And Characteristic Curves**

TYPICAL FORWARD CHARACTERISTIC



FORWARD CURRENT DERATING CURVE



MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

